

X-SPDT SWITCH GaAs MMIC

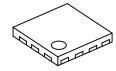
■ GENERAL DESCRIPTION

The NJG1662MD7 is a GaAs X (cross) - SPDT switch MMIC, which is designed for switching of balanced dual band filters.

The NJG1662MD7 features very low phase error between on-state paths, low insertion loss, low control voltage and wide frequency coverage. The ESD protection circuit are integrated in the IC to achieve high ESD tolerance.

The ultra-small and ultra-thin EQFN14-D7 package is adopted.

■ PACKAGE OUTLINE



NJG1662MD7

■ FEATURES

● Low phase error ±3 deg @f=2.0GHz

Low operation voltage
 V_{DD}=+1.5~+4.5V
 Low control voltage
 V_{CTL(H)}=+1.3V min.

■ Low insertion loss
0.3dB typ. @f=1.0GHz, P_{IN}=0dBm

0.4dB typ. @f=2.0GHz, $P_{IN}=0dBm$

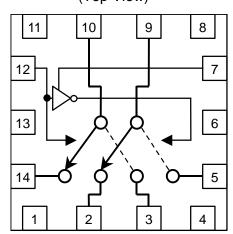
● High isolation 28dB typ. @f=1.0GHz, P_{IN}=0dBm

22dB typ. @f=2.0GHz, P_{IN}=0dBm

● Small and thin package EQFN14-D7 (Package size: 1.6x1.6x0.397mm typ., Lead and Halogen-Free)

■ PIN CONFIGURATION

(Top View)



Pin connection

1. GND 10. PC1 2. PA2 11. GND

3. PB1 12. VCTL

4. GND 13. GND 5. PB2 14. PA1

5. PB2 14. I 6. GND

7. VDD

7. VUU

8. GND

9. PC2

■ TRUTH TABLE

"H"=V_{CTL(H)}. "L"=V_{CTL(L)}

ON PATH	VCTL
PC1-PA1,PC2-PA2	Н
PC1-PB1,PC2-PB2	L

NOTE: The Information on this datasheet will be subject to change without notice.

^{*)} X-SPDT is a paired SPDT switch controlled synchronously. The X-SPDT includes two SPDT switches whose RF lines have a crossing inside the chip.

NJG1662MD7

■ ABSOLUTE MAXIMUM RATINGS

 $(T_a=+25^{\circ}C, Z_s=Z_l=50\Omega)$

PARAMETER	SYMBOL	CONDITIONS	RATINGS	UNITS
RF input power	P _{IN}	V _{DD} =2.7V, VCTL=0V/1.8V PC1,PC2,PA1,PA2,PB1,PB2	28	dBm
Supply voltage	V_{DD}	VDD terminal	5.0	V
Control voltage	V_{CTL}	VCTL terminal	5.0	V
Power dissipation	P_D	On PCB	1300	mW
Operating temp.	T_{opr}		-40~+85	°C
Storage temp.	T_{stg}		-55~+150	°C

■ ELECTRICAL CHARACTERISTICS

 $(General\ conditions:\ T_a=+25^{\circ}C,\ Z_s=Z_l=50\Omega,\ V_{DD}=2.7V,\ V_{CTL(L)}=0V,\ V_{CTL(H)}=1.8V,\ with\ application\ circuit)$ **PARAMETERS** SYMBOL **CONDITIONS** MIN TYP MAX UNITS Supply voltage V_{DD} 1.5 2.7 4.5 V P_{IN}=0dBm Operating current 16 30 I_{DD} μА ٧ Control voltage (LOW) $V_{CTL(L)}$ 0 0.4 Control voltage (HIGH) $V_{CTL(H)}$ 1.3 1.8 V_{DD} ٧ Control current I_{CTI} f=2GHz, P_{IN}=0dBm 5 10 μΑ LOSS1 f=1GHz, P_{IN}=0dBm 0.3 0.45 dB Insertion loss 1 Insertion loss 2 LOSS2 f=2GHz, P_{IN}=0dBm 0.4 0.55 dB PC1-PA1, PC2-PA2 PC1-PB1, PC2-PB2 Isolation 1 ISL1 26 28 dΒ f=1GHz, P_{IN}=0dBm PC1-PA1, PC2-PA2 ISL2 PC1-PB1, PC2-PB2 20 22 dΒ Isolation 2 f=2GHz, $P_{IN}=0dBm$ PC1-PA1, PC2-PA2 PC1-PB1, PC2-PB2 Isolation 3 ISL3 18 20 dΒ f=2.5GHz, P_{IN}=0dBm PC1-PC2 port ISL4 Isolation 4 26 28 dB f=2GHz, P_{IN}=0dBm PΕ f=2GHz, between on paths -3 0 3 Phase error deg Input power at 0.2dB $P_{\text{-}0.2dB}$ f=2GHz 20 24 dBm compression point **VSWR VSWR** f=2GHz, On port 1.2 1.3 Switching time T_{SW} 50% CTL to 10%/90% RF 1.5 5.0 μS

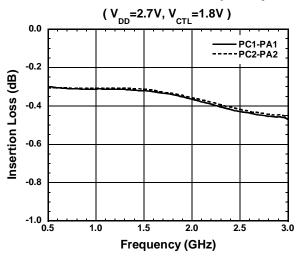
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■ TERMINAL INFORMATION

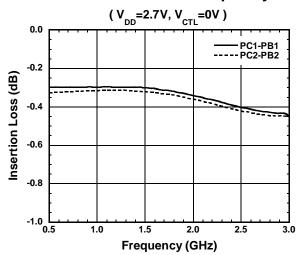
No.	SYMBOL	DESCRIPTION	
1	GND	Ground terminal. Please connect this terminal with ground plane as close as possible for good RF performance.	
2	PA2	This port is connected to PC2 terminal by applying High-level (1.3~4.5V) at VCTL terminal. An external capacitor is required to block DC voltage of internal circuit.	
3	PB1	This port is connected to PC1 terminal by applying Low-level (0~0.4V) at VCTL terminal. An external capacitor is required to block DC voltage of internal circuit.	
4	GND	Ground terminal. Please connect this terminal with ground plane as close as possible for good RF performance.	
5	PB2	This port is connected to PC2 terminal by applying Low-level (0~0.4V) at VCTL terminal. An external capacitor is required to block DC voltage of internal circuit.	
6	GND	Ground terminal. Please connect this terminal with ground plane as close as possible for good RF performance.	
7	VDD	A supply voltage terminal (1.5~4.5V). Please place a bypass capacitor between this terminal and GND for avoiding RF noise from outside.	
8	GND	Ground terminal. Please connect this terminal with ground plane as close as possible for good RF performance.	
9	PC2	Common RF port. This port is connected with either of PA2 or PB2. An external capacitor is required to block DC voltage of internal circuit.	
10	PC1	Common RF port. This port is connected with either of PA1 or PB1. An external capacitor is required to block DC voltage of internal circuit.	
11	GND	Ground terminal. Please connect this terminal with ground plane as close as possible for good RF performance.	
12	VCTL	Control signal input terminal. This terminal is set to high-level (1.3V~4.5V) or low-level (0~0.4V).	
13	GND	Ground terminal. Please connect this terminal with ground plane as close as possible for good RF performance.	
14	PA1	This port is connected to PC1 terminal by applying High-level (1.3~4.5V) at VCTL terminal. An external capacitor is required to block DC voltage of internal circuit.	

■ ELECTRICAL CHARACTERISTICS (With Application circuit, Loss of external circuit are excluded)

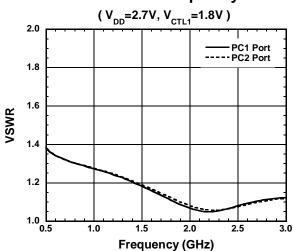
Insertion Loss vs. Frequency



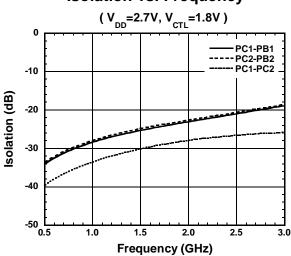
Insertion Loss vs. Frequency



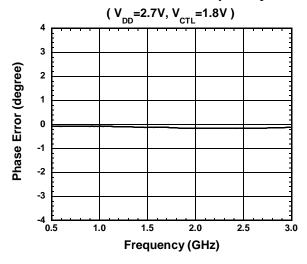
VSWR vs. Frequency



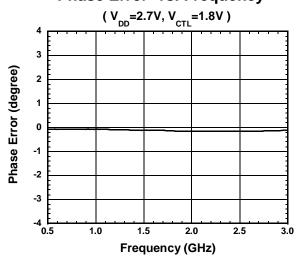
Isolation vs. Frequency



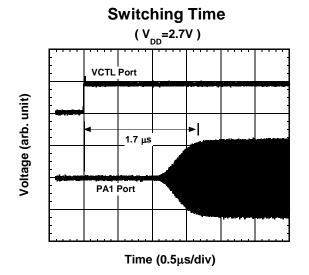
PC1-PA1, PC2-PA2 Phase Error vs. Frequency

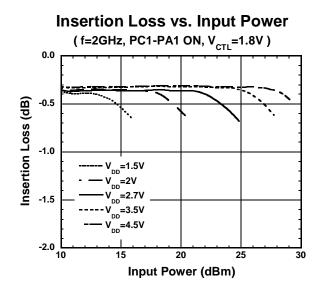


PC1-PA1, PC2-PA2
Phase Error vs. Frequency

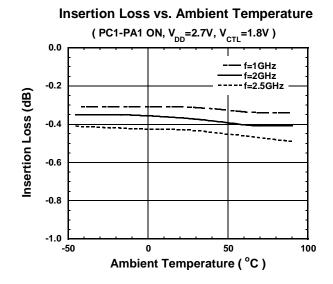


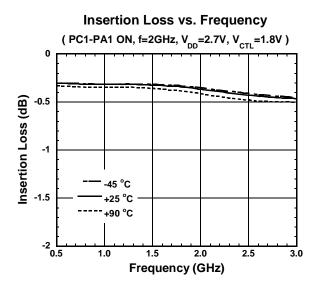
■ ELECTRICAL CHARACTERISTICS (With Application circuit, Loss of external circuit are excluded)

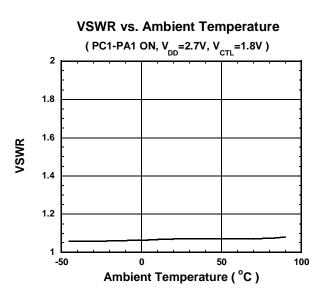


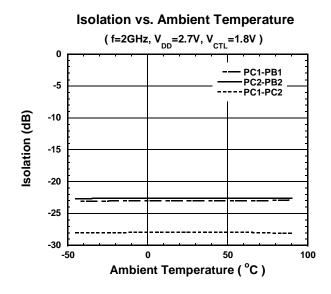


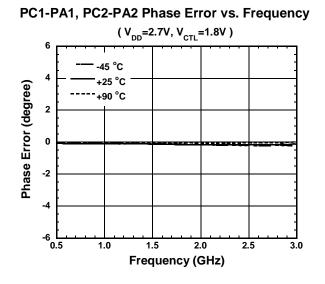
■ ELECTRICAL CHARACTERISTICS (With Application circuit, Loss of external circuit are excluded)

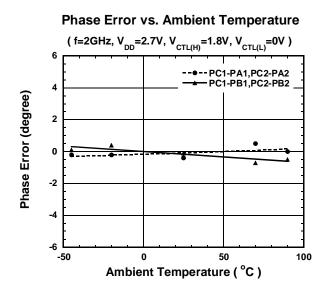




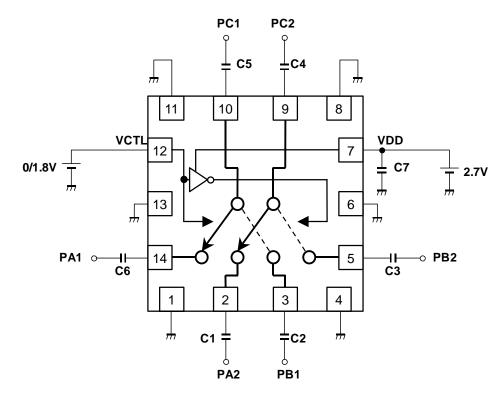








■ APPLICATION CIRCUIT

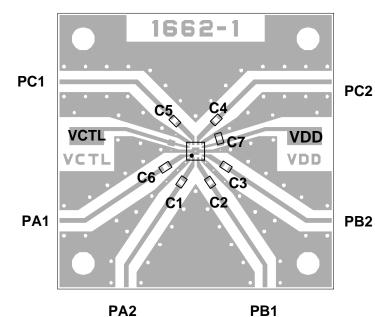


■ PARTS LIST

Part ID	Value	Notes	
C1~C6	56pF	MURATA (GRM15)	
C7	1000pF		

■ TEST PCB LAYOUT

(TOP VIEW)



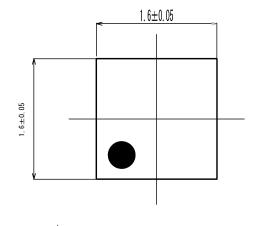
PCB: FR-4, t=0.2mm

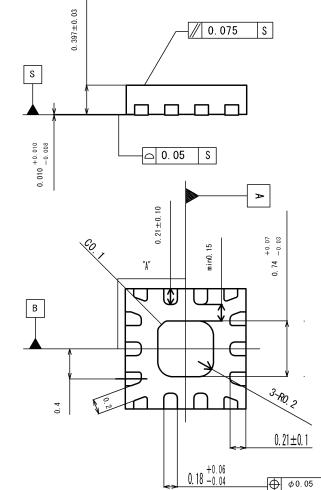
Capacitor Size: 1005
Strip Line Width: 0.4mm
PCB Size: 26 x 26mm

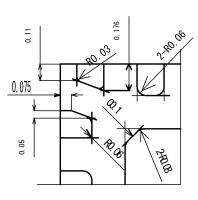
Losses of PCB, capacitors and connectors

Frequency (GHz)	Loss (dB)
1.0	0.38
2.0	0.51
2.5	0.55

■ PACKAGE OUTLINE (EQFN14-D7)







Details of "A" part (\times 2)

Units : mm : Cu **Board**

Terminal treat : SnBi

Molding material: Epoxy resin

Weight : 3.3mg

Cautions on using this product

This product contains Gallium-Arsenide (GaAs) which is a harmful material.

- Do NOT eat or put into mouth.
- Do NOT dispose in fire or break up this product.
- Do NOT chemically make gas or powder with this product.
- To waste this product, please obey the relating law of your country.

This product may be damaged with electric static discharge (ESD) or spike voltage. Please handle with care to avoid these damages.

[CAUTION]
The specifications on this databook are only given for information, without any guarantee as regards either mistakes or omissions. The application circuits in this databook are described only to show representative usages of the product and not intended for the guarantee or permission of any right including the industrial rights.

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